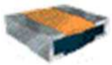
景碩科技股份有限公司

Kinsus Interconnect Technology Co.

2013 Nov

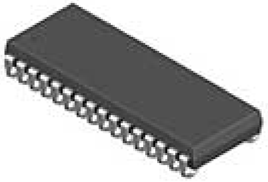
IC 封裝技術
IC Packaging Technology

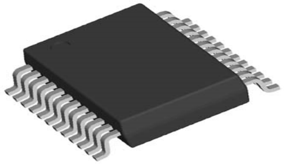
各種形式的 IC 封裝

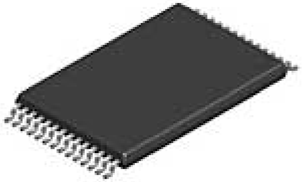

Chips

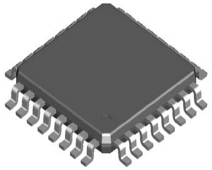

SOT/SOD

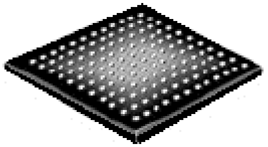

DPAK

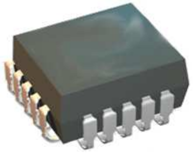

SOJ

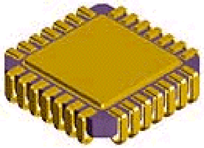

SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP


TSOP


OFP/TOFP
/LOFP


BGA/Flip-Chip
/WLP


PLCC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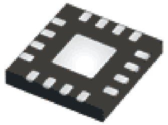
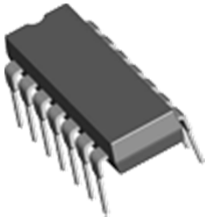

QFN


DFN

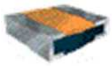

DIP


Axial


Radial

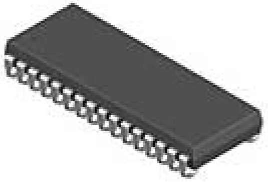
Through-hole

Different types of IC packaging


Chips


SOT/SOD


DPAK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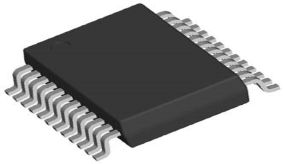
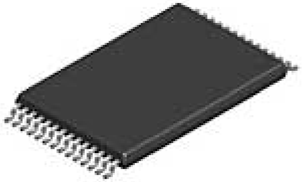
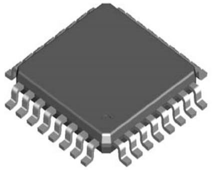
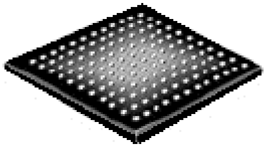
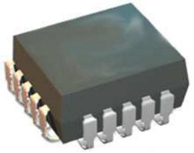
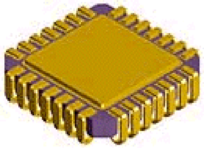

SOIC/SSOP/
OSOP/TSSOP/
MSOP/HSOP

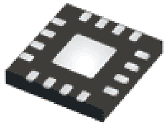

TSOP


OFP/TOFP
/LOFP

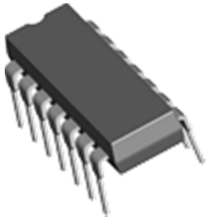

BGA/Flip-Chip
/WLP


PLCC


CLCC


QFN


DFN

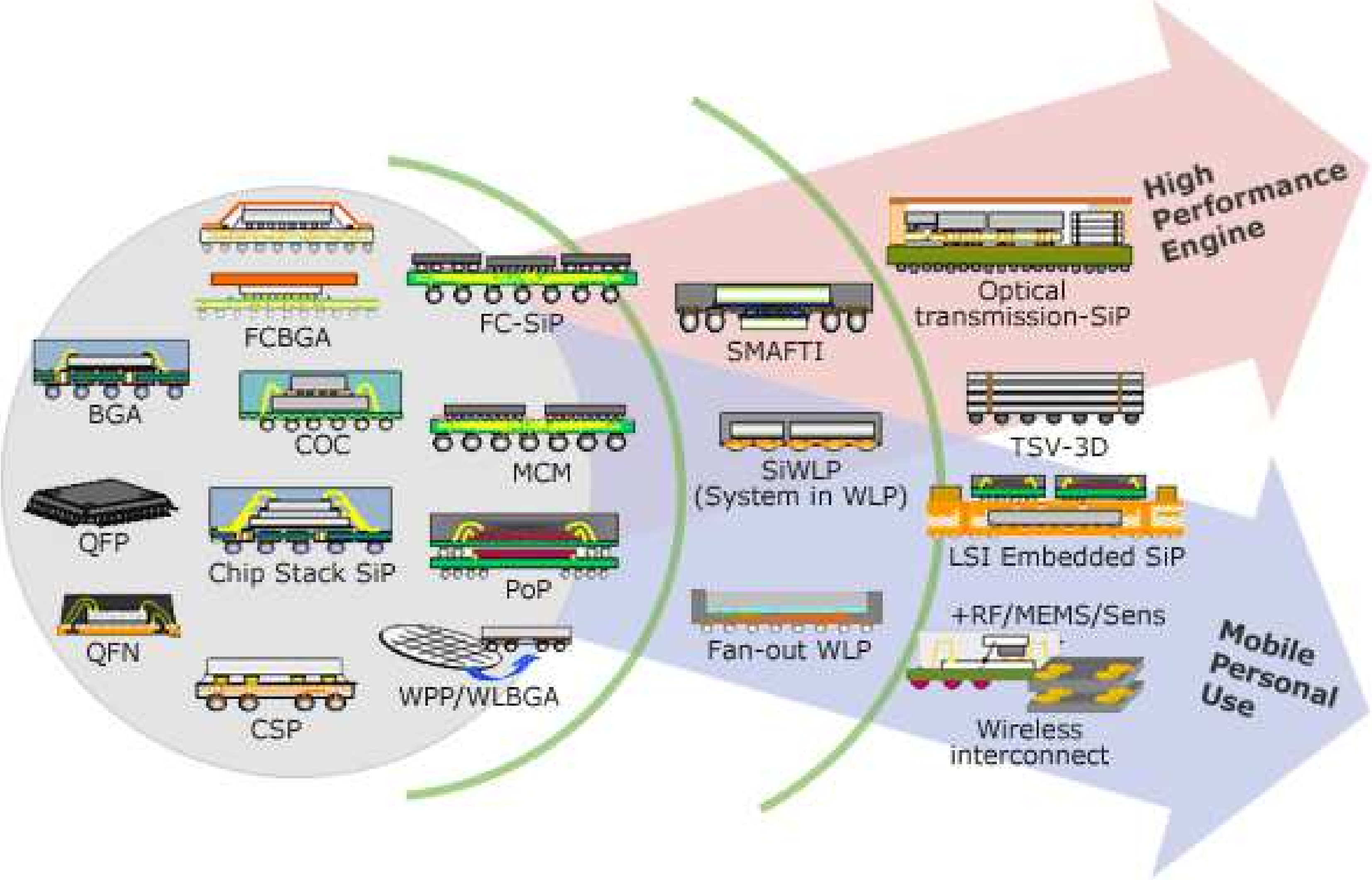

DIP


Axial

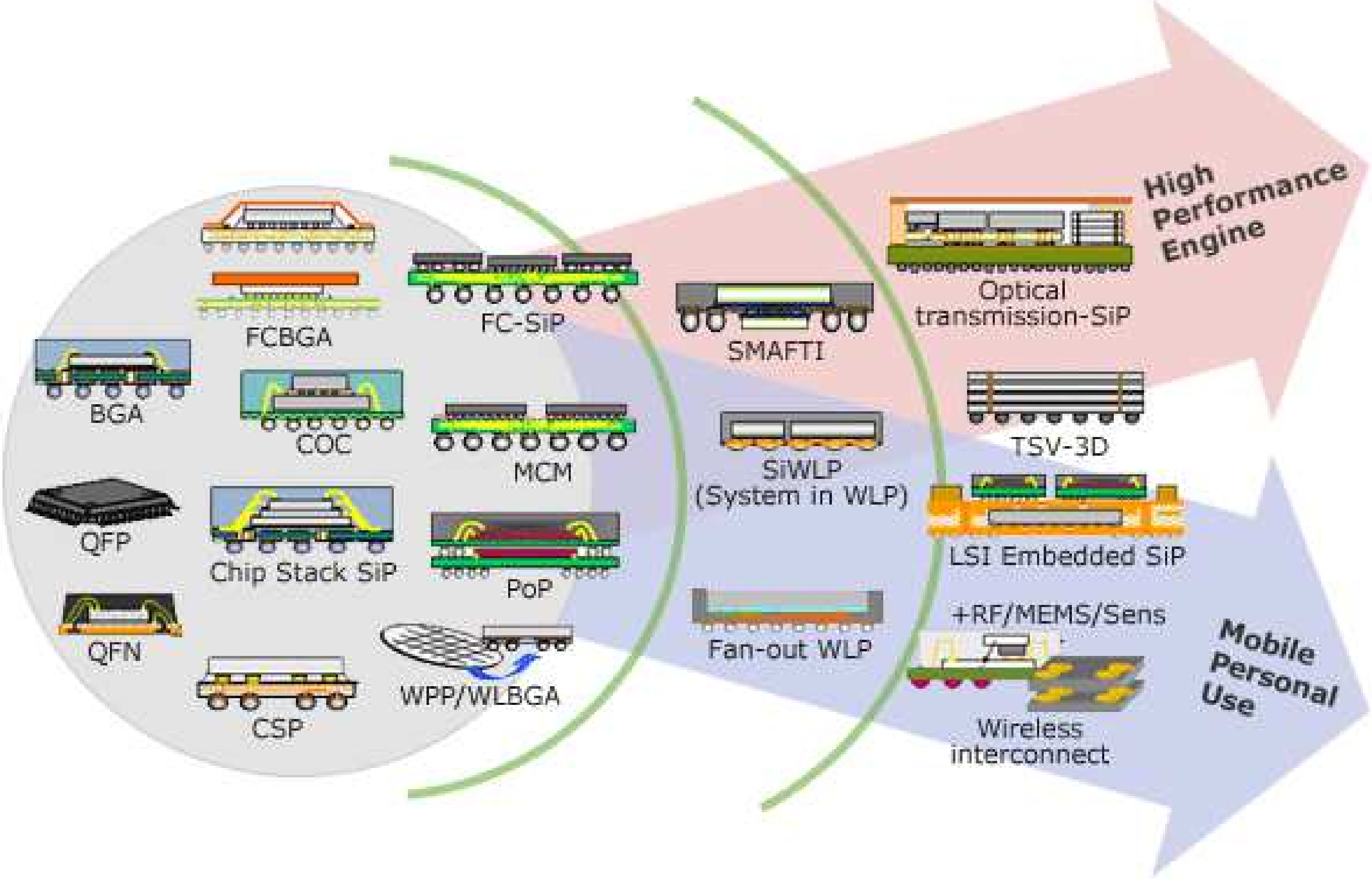

Radial

Through-hole

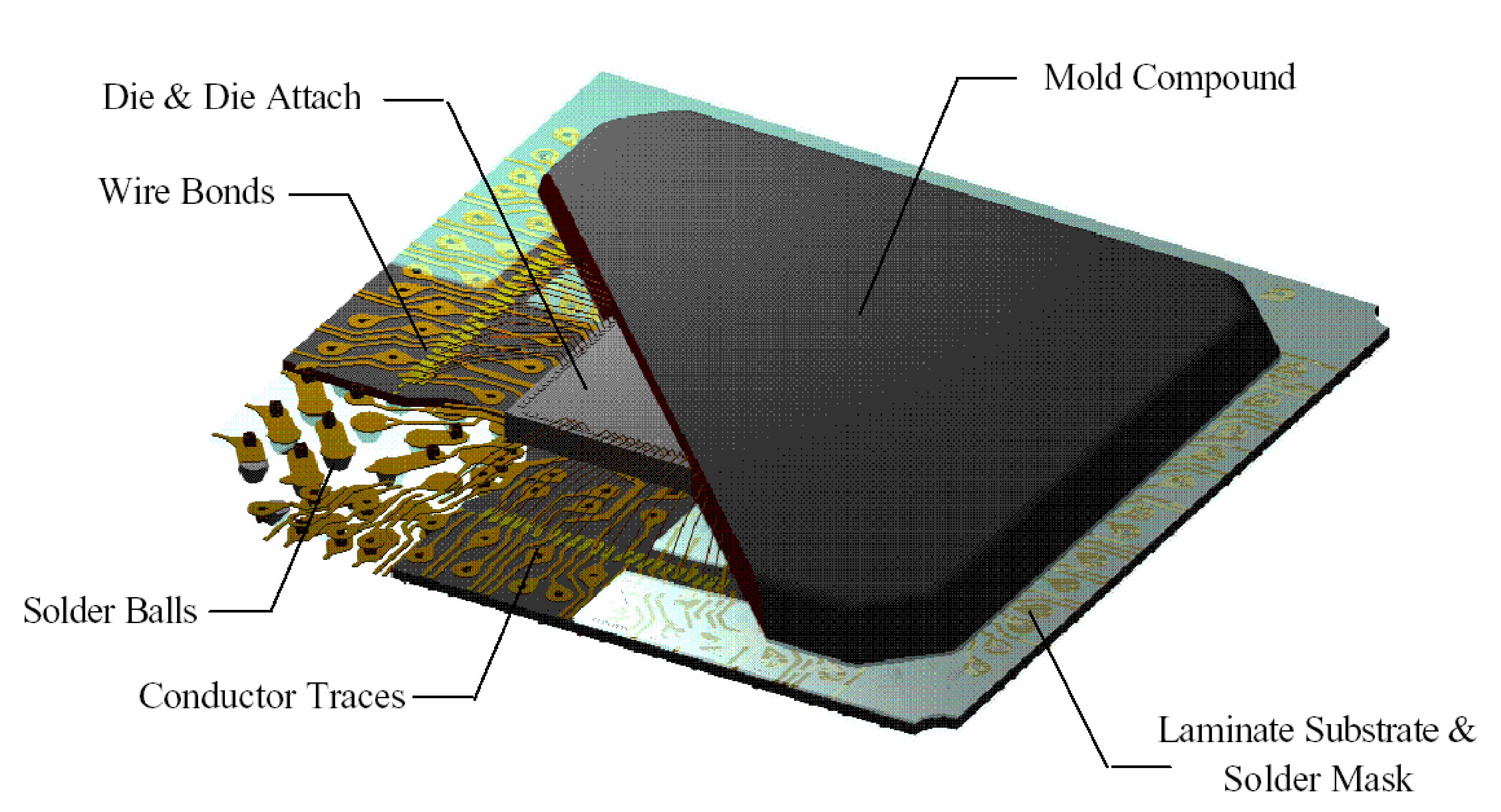
封裝技術走向


FCBGA
FC-SiP
BGA
COC
MCM
QFP
Chip Stack SiP
PoP
QFN
CSP
WPP/WLBGA
SMAFTI
SiWLP
(System in WLP)
Fan-out WLP
Optical
transmission-SiP
High
Performance
Engine
TSV-3D
LSI Embedded SiP
+RF/MEMS/Sens
Wireless
interconnect
Mobile
Personal
Use

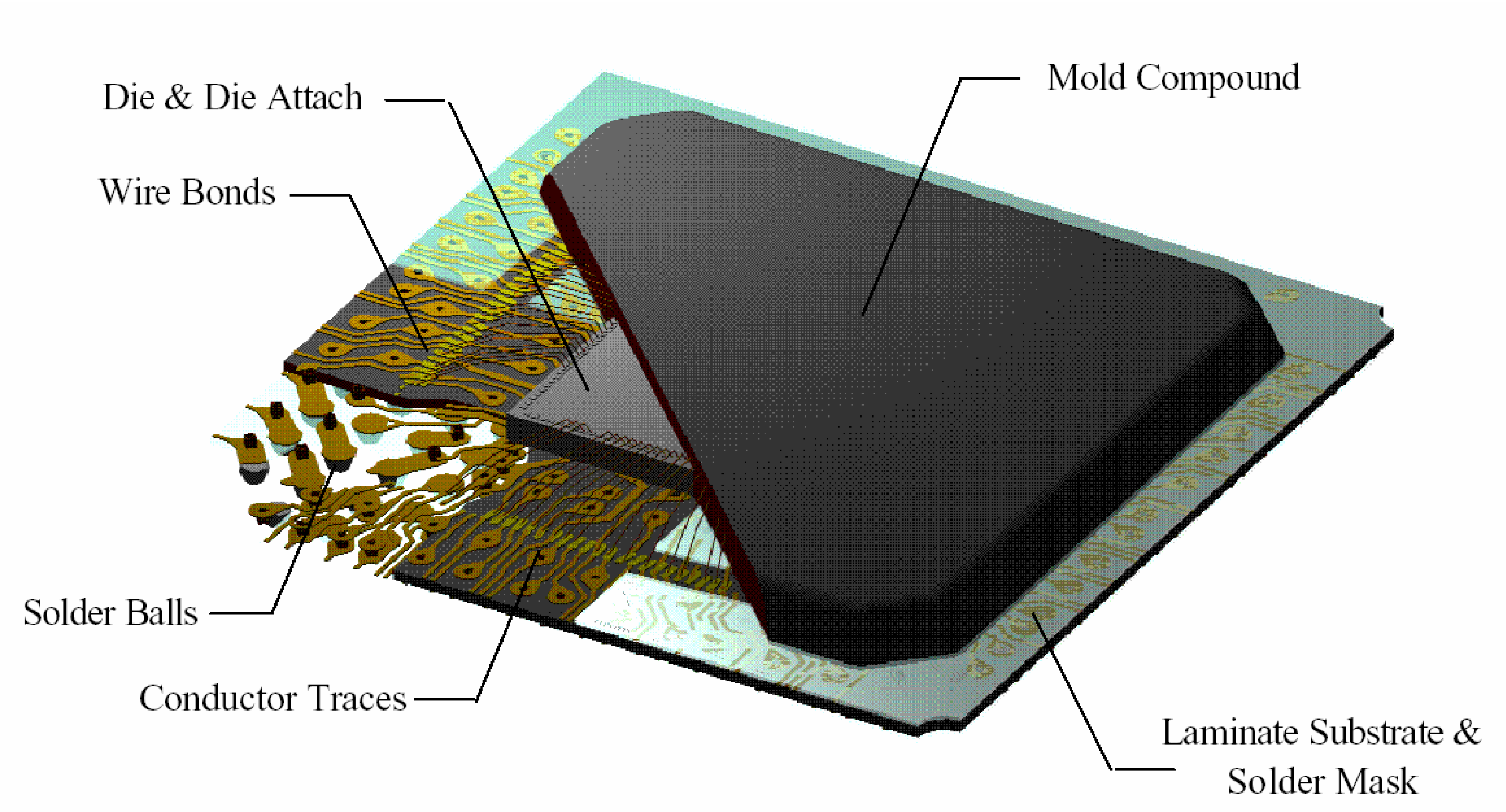
Packaging Technology Roadmap



IC 結構


Die & Die Attach
Wire Bonds
Mold Compound
Solder Balls
Conductor Traces
Laminate Substrate &
Solder Mask

What Substrate Makers do?



About Kinsus

基本資料

- 成立September 2000
  上市 November 2004
- 登記資本額 新台幣 44.6 億
- 員工數 : 3,500 （2013 十月）
- 廠區 :
  - 總部 - 石磊 / 新屋鄉
  - 硬質載板事業部 - 一廠
    - 二廠 -A 及 -B
  - 軟質載板事業部 - 三廠
  - 美國子公司 - Santa Clara / California
  - 中國子公司 - 蘇州

Basic Information

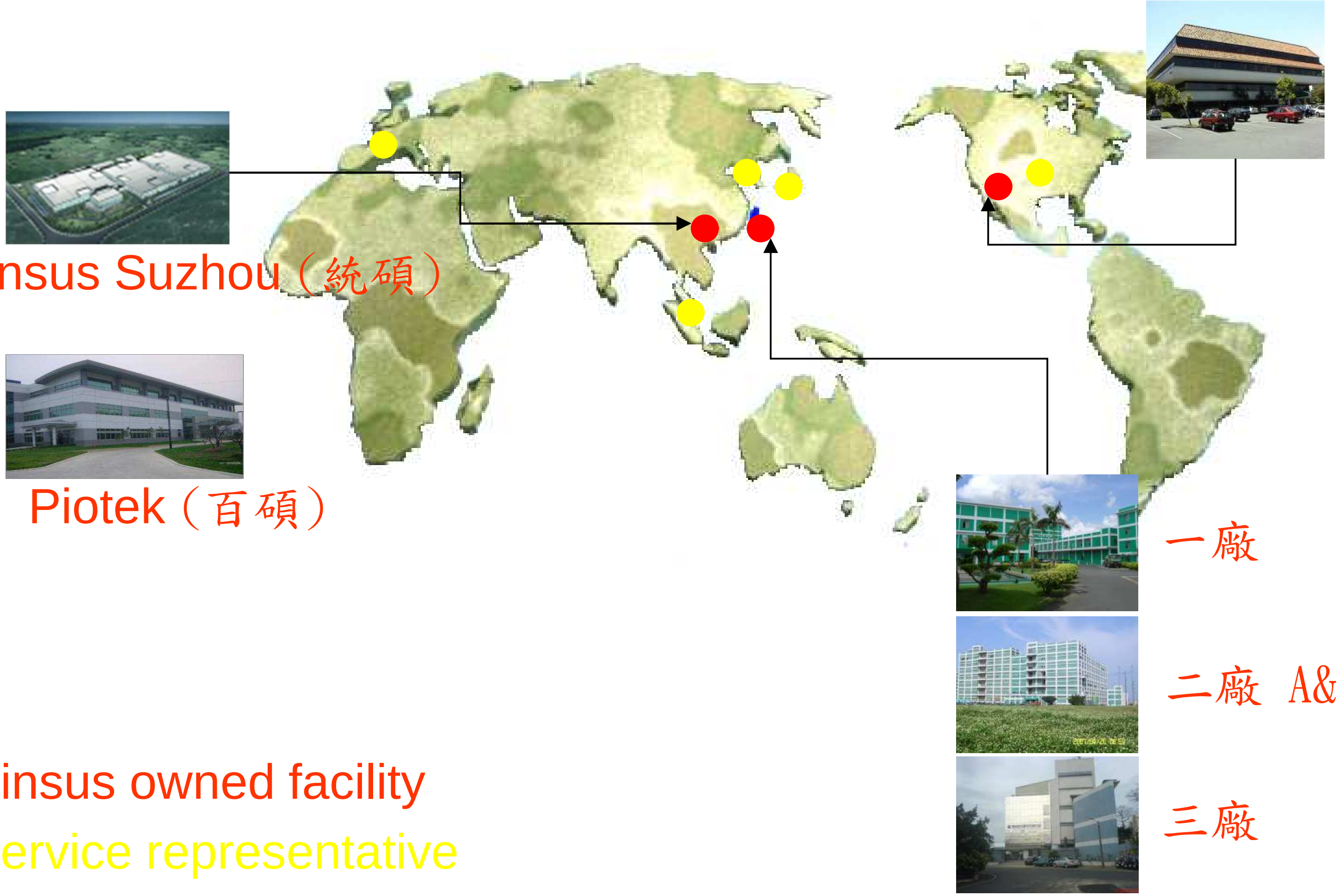
- Established in September 2000
  IPO in November 2004

- Capital : US$ 154 Million (NT$ 4.46 Billion)

- Headcounts : 3,500 as of Oct 2013

- Campus :
  Headquarters - Shih Lei / Sin Wu
  Rigid Substrates BU - Plant I
  - Plant II-A & -B
  Flexible Substrate BU - Plant III
  Kinsus USA - Santa Clara / California
  Kinsus China - Suzhou

位置



美國子公司

Kinsus Suzhou（統碩）

Piotek（百碩）

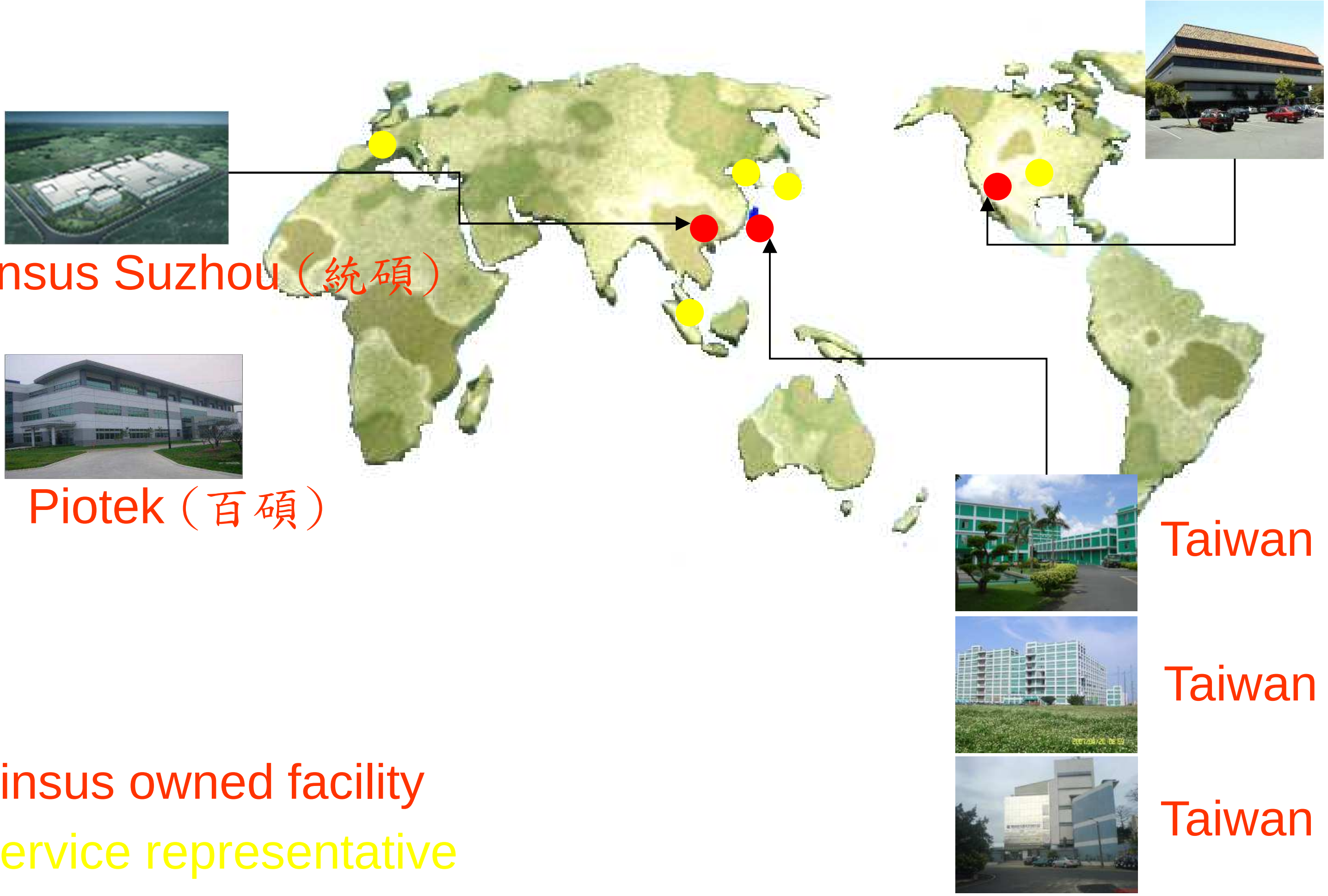
一廠

二廠 A&B

三廠

- 🟥 Kinsus owned facility
- 🟨 Service representative

Locations



Kinsus USA

Kinsus Suzhou（統碩）

Piotek（百碩）

Taiwan plant I

Taiwan plant II-A & B

Taiwan plant III

- ● Kinsus owned facility
- ● Service representative

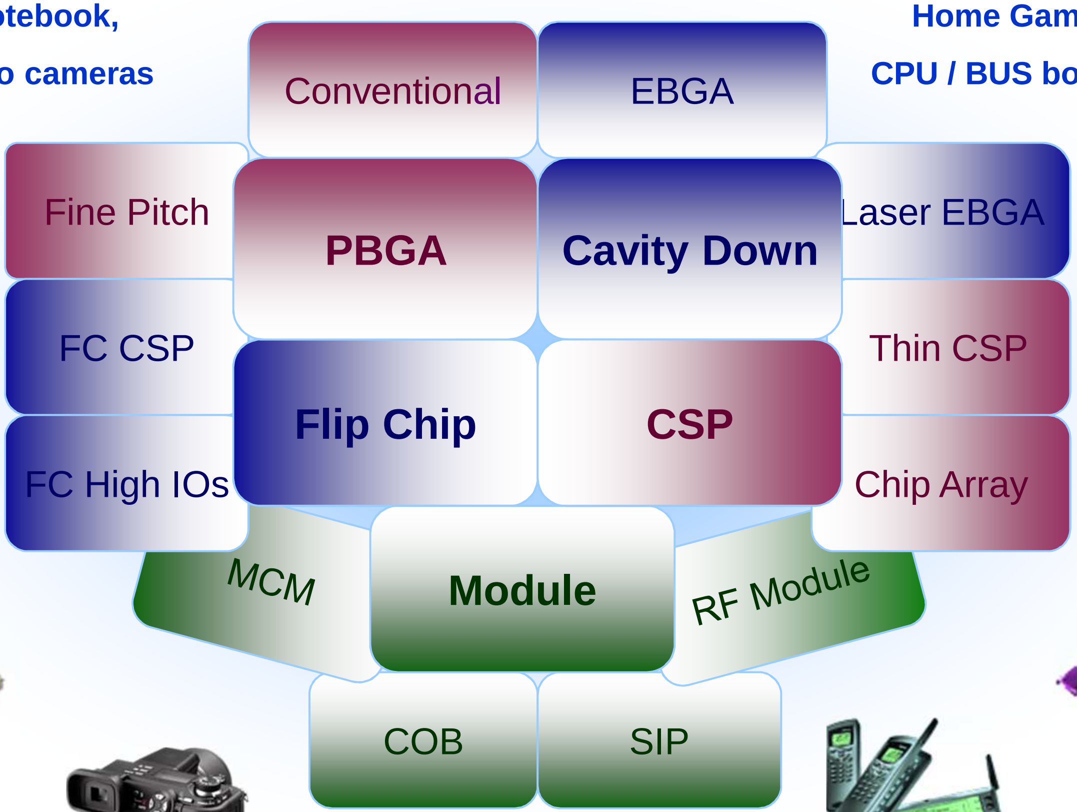
硬質載板產品

Kinsus Tech.

Desk Top,
PCMCIA cards,
notebook,
video cameras




Server, Switch,
Set-Top Box,
Home Game,
CPU / BUS boards

Digital camera,
Cellular,
wireless,
MP3 Player,
DROM




Rigid Substrate Products

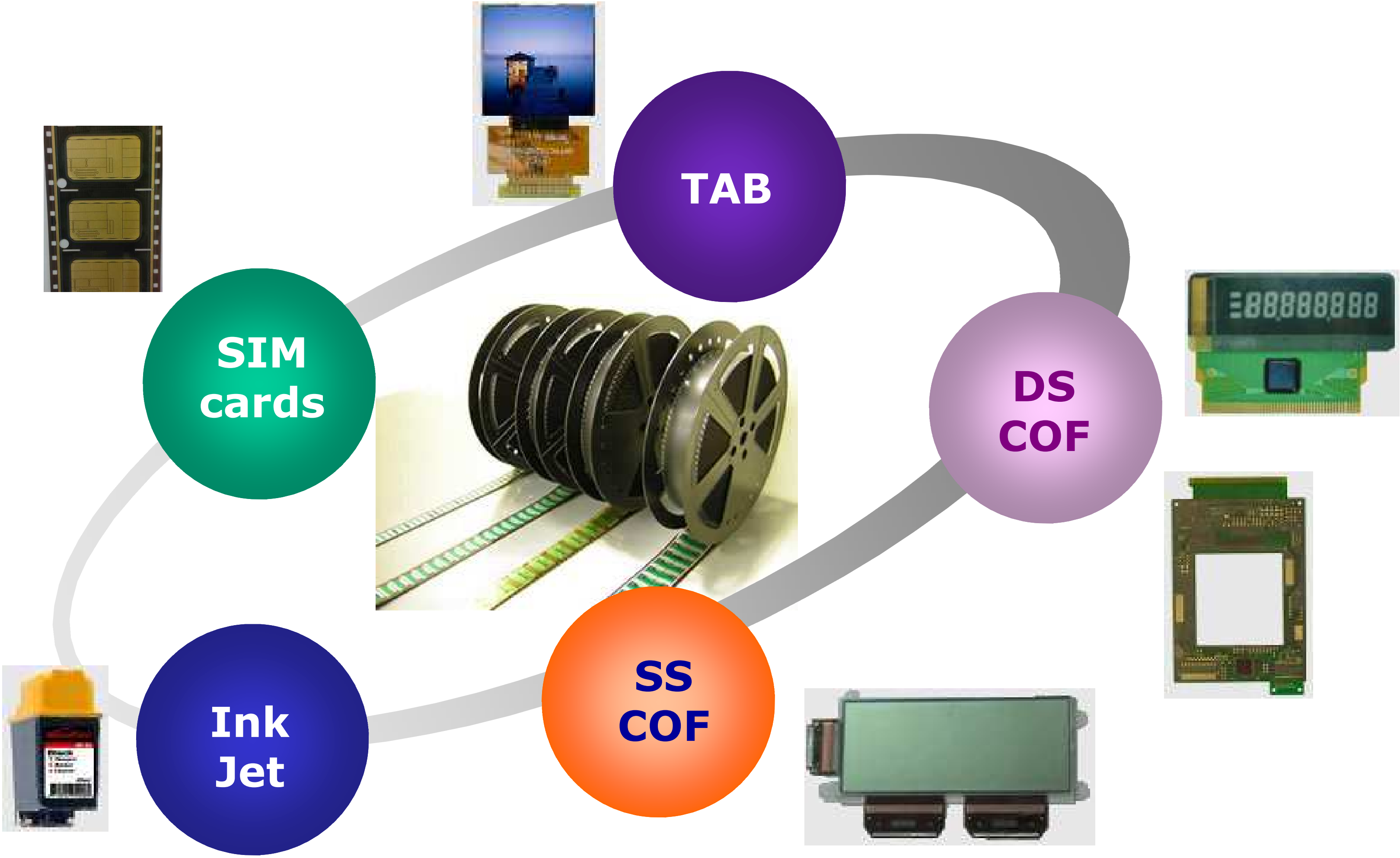
Desk Top,
PCMCIA cards,
notebook,
video cameras

Server, Switch,
Set-Top Box,
Home Game,
CPU / BUS boards

Conventional
EBGA
Fine Pitch
PBGA
Cavity Down
Laser EBGA
FC CSP
Thin CSP
Flip Chip
CSP
FC High IOs
Chip Array
MCM
Module
RF Module
COB
SIP

Digital camera,
Cellular,
wireless,
MP3 Player,
DROM

軟質載板產品



TAB

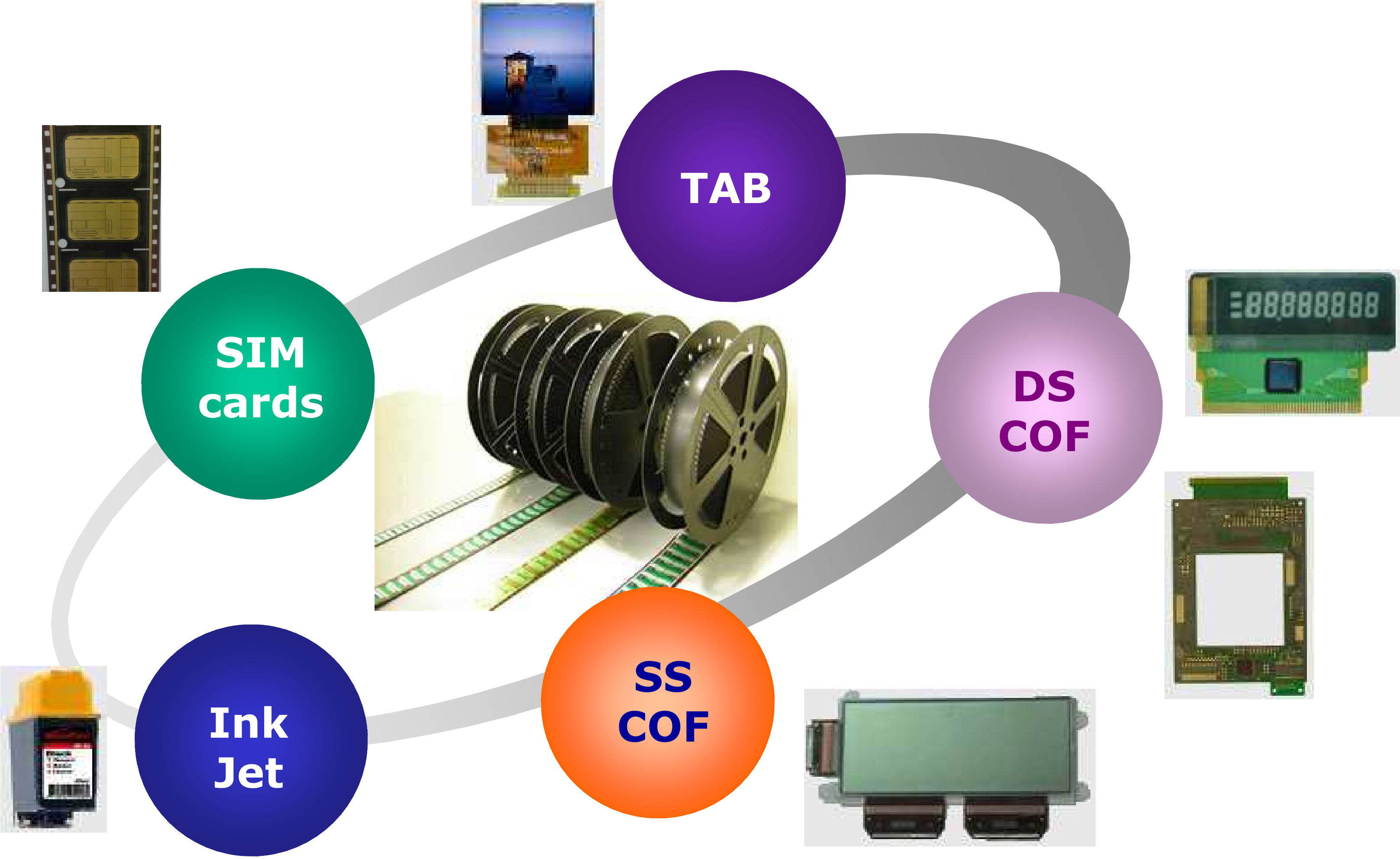
SIM cards

DS COF

SS COF

Ink Jet

Flexible Substrate Products


TAB

SIM cards

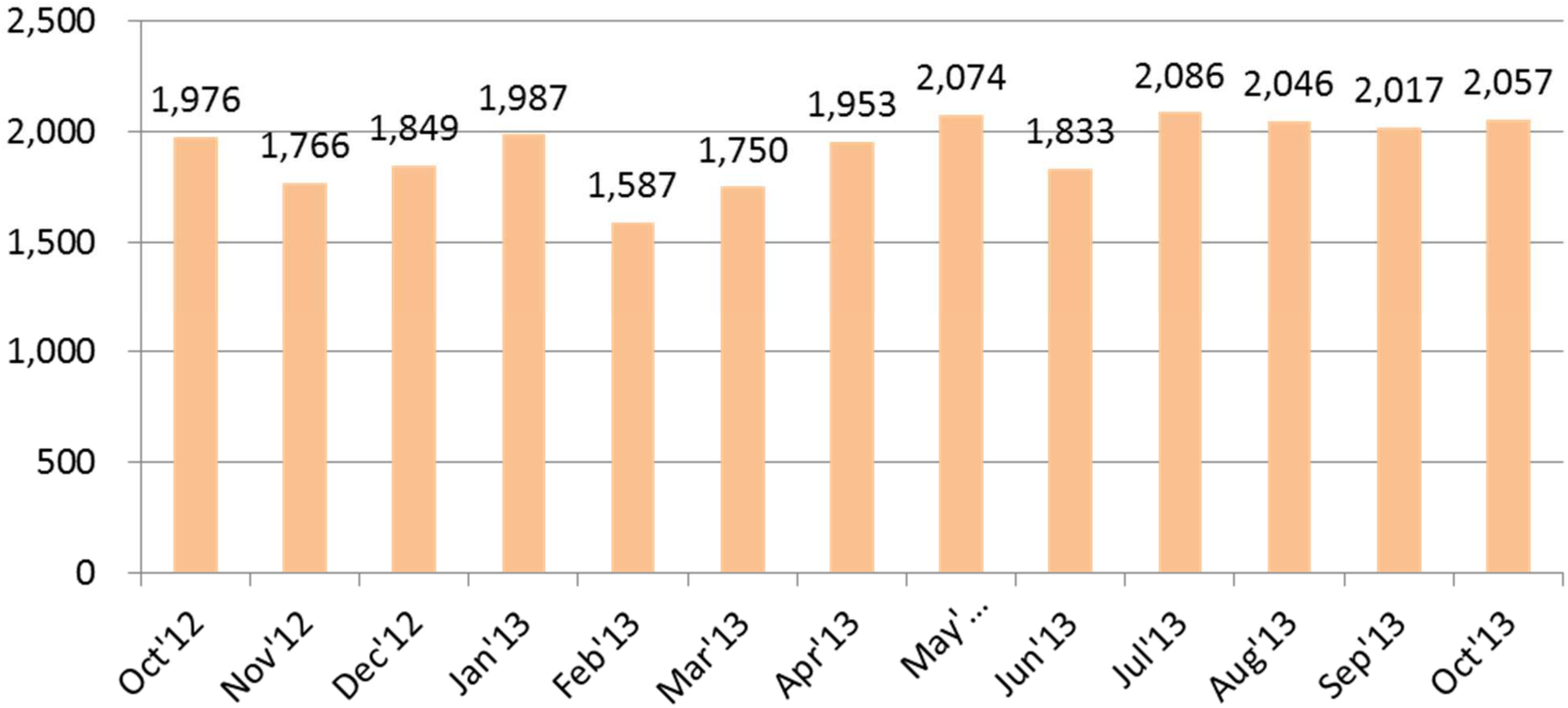
DS COF

SS COF

Ink Jet

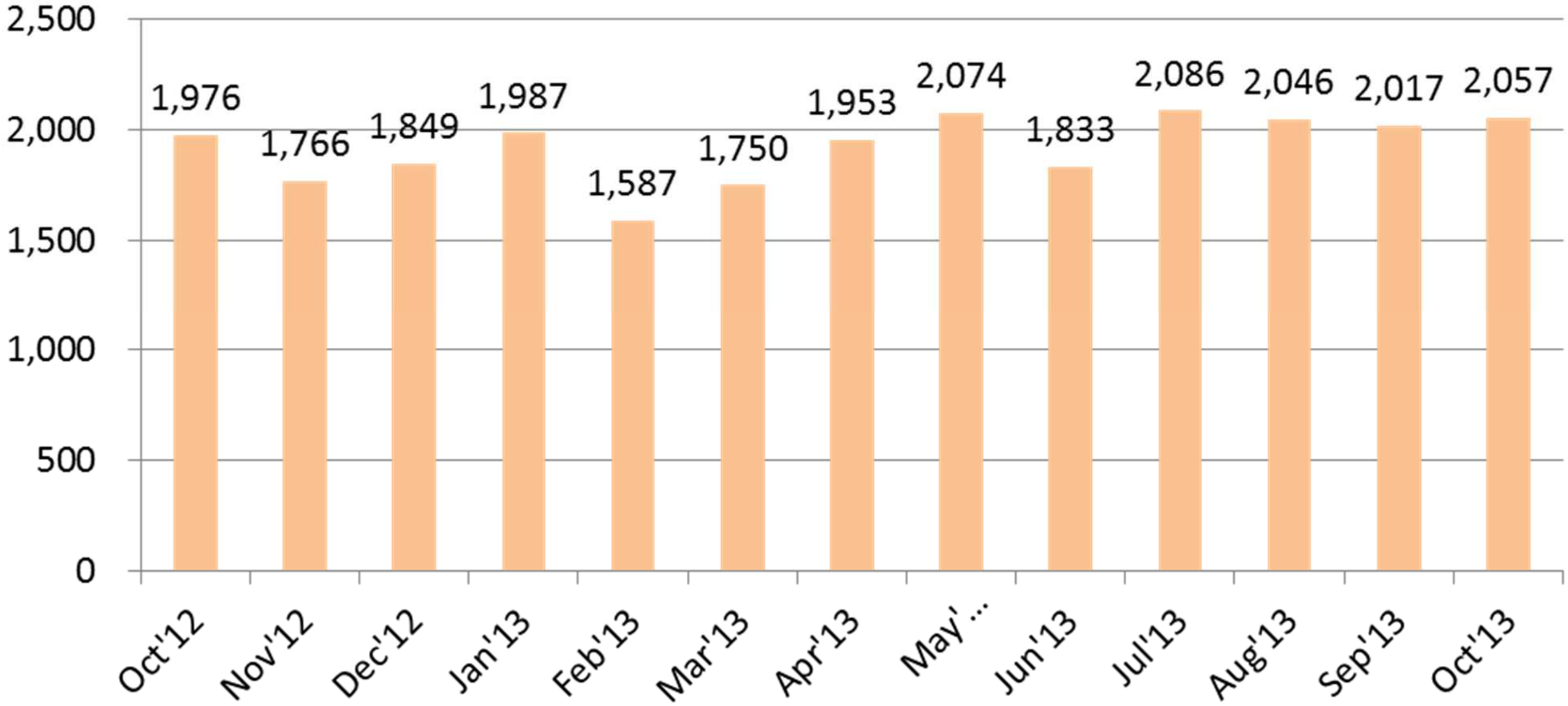
每月營業額

單位 ： 新台幣百萬元



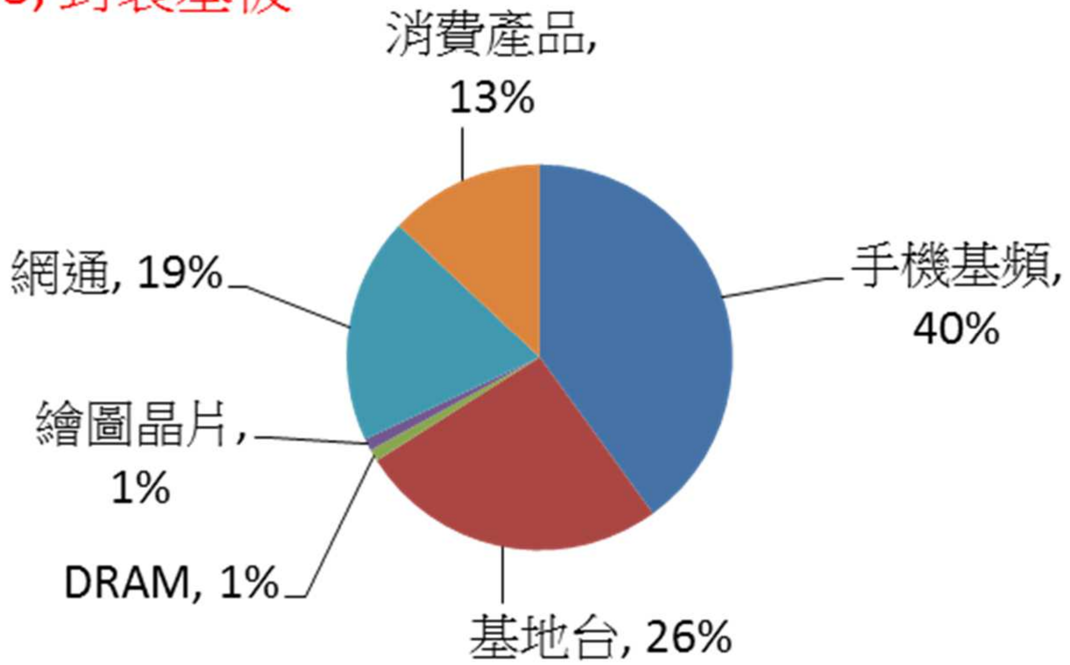
Monthly Revenue

Unit : Million NT$



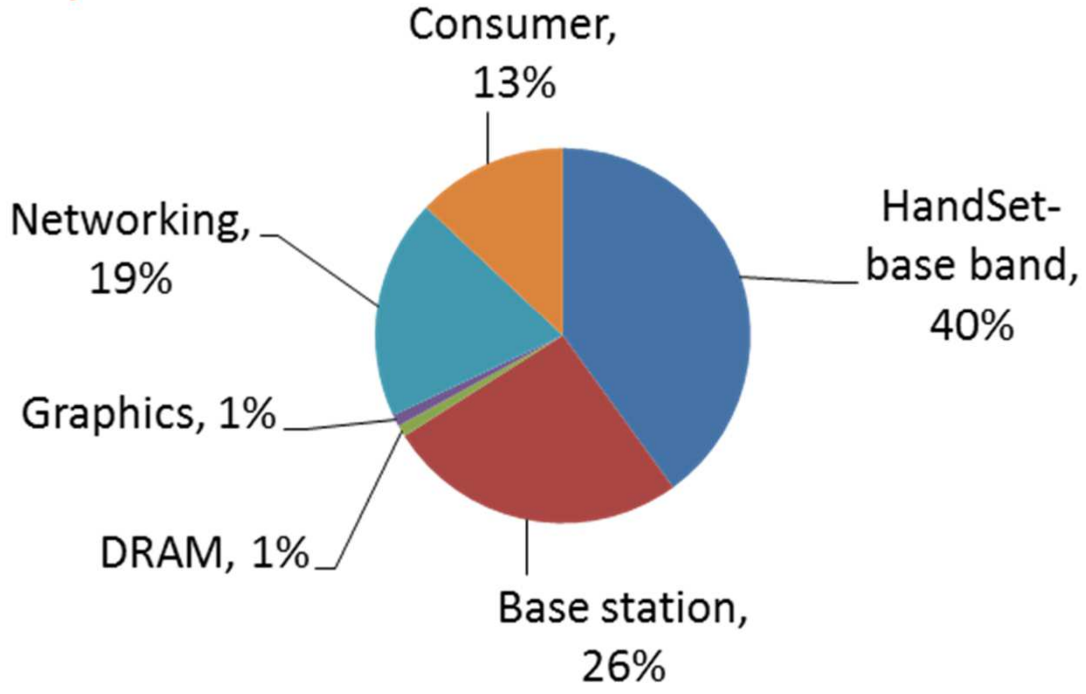
營業額分佈

Q3,2013, 封裝基板



Revenue - Application

Q3,2013, substrates



Thank You!